

Q237 Requirements for Printed Wiring Boards/Flex Circuits RS68 Program Only  
- rev 6/14/01

The following requirements are imposed for the procurement of printed wiring boards and multilayer flex circuits:

1. When specified on this Purchase Contract as Q203, Buyer in-process source inspection is required as follows:
  - o Detail stage source inspection unless automated optical inspection is performed or waived by Boeing's Quality Engineering responsible personnel in writing.
  - o After etch before soldermask, unless waived by Boeing's Quality Engineer in writing.
  - o Final Source Inspection shall be performed (single sided, double sided, multilayer, rigid flex) after route and test.
2. All coupons, cross sections, Process Producibility Analysis (PPA) specimens and X-rays (when required). etc., must be traceable to individual printed wiring boards and must accompany each shipment. (Note that all X-ray requirements are after drill operation prior to electroless nickel copper plate and that the X-rays must be wet film).

A copy of the supplier's test reports analysis for microsections ("Group A") must accompany the test coupons and microsections shipped to Boeing. (A copy of the shop traveler must be sent along with certifications, when requested). Serial numbers must also be on the packer.

Multilayer boards and flex circuits require Boeing El Paso's M&P lab approval prior to any further assembly operations (i.e. next assy. level, heatsinks, etc.). Test coupons and microsections shall be delivered to Boeing El Paso, Attention M&P Lab for analysis and approval by Engineering prior to subsequent assembly operations.

When shipments are split, or when the cross-sections are Gang-mounted, note the date of original shipment on the packer.

3. When PPA test boards are required per lot, ship the PPA board to Boeing El Paso's receiving location with the first delivery from the lot.